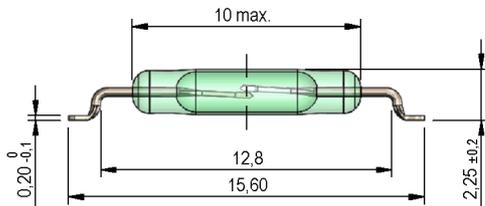


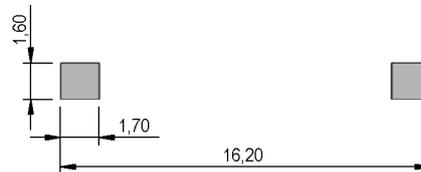
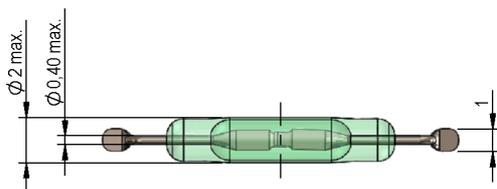
Dimensions mm[inch]
tolerances according to DIN ISO 2768-m
Toleranzen gem. DIN ISO 2768-m



Isometric
Scale 2:1
Maßstab 2:1

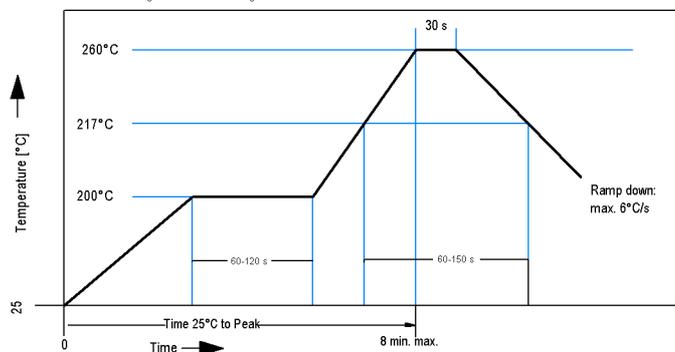


Recommended PCB Pad Layout

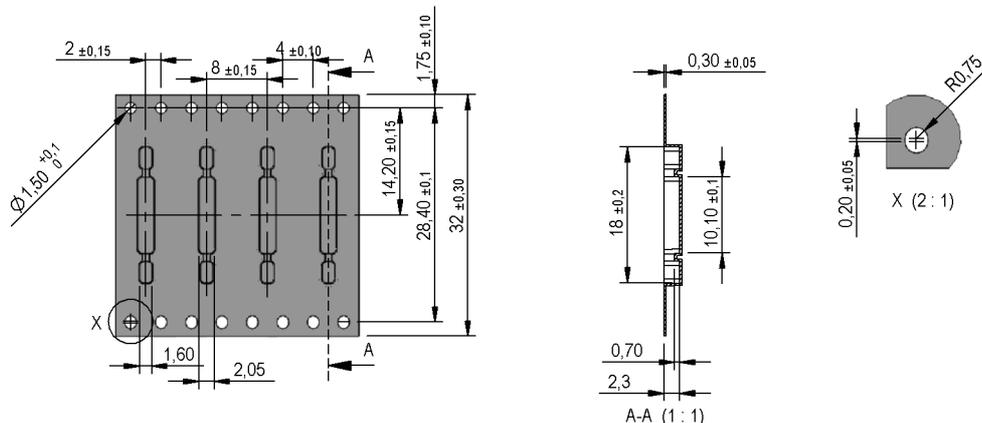


Solder Reflow Profile

reflow soldering conditions according to JEDEC norm J-STD 020D.1



Packaging





Europe: +49 / 7731 8399 0

| Email: info@standexmeder.com

Item No.:

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9231871015

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Item:

MK23-87-B-2

Magnetic properties	Conditions	Min	Typ	Max	Unit
Pull-In excitation (Reference value)	Reed switch unmodified measured in coil- "define operation"	10		15	AT
Test equipment	Testing 100%	KMS-01			
Pull-In excitation (modified contact)	Reed switch modified phys. conditioned tolerance of +/- 1 AT	18		28	AT
Test equipment	Testing 100%	KMS-22			
Pull-In in milliTesla (modified contact)	MS150 - phys. caused tolerance +/- 0,1mT	1,14		2,13	mT

Contact data 87	Conditions	Min	Typ	Max	Unit
Contact-form		A			
Contact-material	Plating thicknesses are proprietary	Rhodium			
Contact rating	Any DC combination of V & A not to exceed their individual max.'s			10	W
Switching voltage	DC or Peak AC			200	V
Switching current	DC or Peak AC			0,4	A
Carry current	DC or Peak AC			0,5	A
Contact resistance static	Measured with 40% overdrive Start Value			150	mOhm
Contact resistance dynamic	Maximum value 1,5 ms after excitation Start Value			200	mOhm
Insulation resistance	RH <45 %, 100V - to all points	1			GOhm
Breakdown voltage	according to IEC 255-5	230			VDC
Operate time incl. bounce	measured with 40% overdrive			0,6	ms
Release time	measured with no coil excitation			0,1	ms
Capacitance	@ 10 kHz across open switch		0,2		pF

Special Product Data	Conditions	Min	Typ	Max	Unit
Reach / RoHS conformity		yes			

Environmental data	Conditions	Min	Typ	Max	Unit
Shock	1/2 sine, duration 11ms, in 3 axis			50	g
Vibration	from 10 - 2000 Hz			20	g
Operating temperature		-40		130	°C
Storage temperature		-55		130	°C
Soldering Temperature Tsold	Reflow according IPC/JEDEC J-STD-020C			260	°C

General data	Conditions	Min	Typ	Max	Unit
Packaging		Tape & Reel 2500 pcs.			

Modifications in the sense of technical progress are reserved

Designed at: 02.04.08 Designed by: AKELLER

Approval at: 24.06.08 Approval by: RKAMP

Last Change at: 12.05.17 Last Change by: DVUCKOVIC

Approval at: 12.05.17 Approval by: DVUCKOVIC

Version: 08